



Company Announcement

Release date 26 March 2025

Chairs Address

Audio Pixels Holdings Limited (ASX: AKP) provide Audio Pixels Holdings Limited Chairman Mr. Fred Bart's address to the 2023 Annual General Meeting.

This announcement has been approved by the Chairman.

Mr Fred Bart
Chairman



Chairmans Address

Good afternoon, and welcome to the 2023 Annual General Meeting of Audio Pixels Holdings Limited. We plan to hold an additional shareholders' meeting toward the end of May of this year to cover the 2024 reporting period.

First and foremost, I want to express my sincere gratitude to our financial backers and shareholders for their patience and unwavering support as we continue our mission to revolutionize the multibillion-dollar sound reproduction industry. I also extend my deep appreciation to all our employees for their continued dedication and contributions, which are instrumental in driving our progress.

Our primary focus remains on advancing our groundbreaking Digital Sound Reconstruction (DSR) platform toward mass production and commercialization. As previously reported, significant efforts have been dedicated to achieving consistent, scalable, and reliable production of our devices—ensuring that they adhere to the stringent design specifications that are required to meet the performance expectations.

To safeguard our long-term success and mitigate potential risks, we have undertaken a strategic reassessment and diversification of our supply chain, particularly to eliminate sole-source dependencies.

While our early collaboration with EarthMountain on Gen-I devices generated significant optimism, their repeated attempts to fabricate Gen-II chips has so far proven to be far more challenging. Recognizing their ongoing difficulties, management undertook a strategic decision to develop our own fabrication process flow for Gen-II MEMS.

Our direct involvement in the most intricate of fabrication details has already yielded exceptional results, allowing us to progress from commencement to deliverables in record time. Initial wafers and chips, expected toward the end of Q2 of this year, will not only be used to meet the continued strong customer and market demand for our product, but to rapidly deploy its fabrication at multiple foundries worldwide.

It is rather unconventional for a fabless semiconductor company like ours to undertake the development of a fabrication process flow, nonetheless we concluded that this was the most effective and expedient solution to overcome the challenges foundries face when dealing with the unique requirements of our devices. Moreover, control and ownership of a fully tried and tested fabrication process flow will provide the company with far greater flexibility and appeal, supporting a foundries decision and efforts to mass produce our devices.

Additionally, and in parallel with the completion of our new, more compact speaker chip package, we have recently authorized the tape-out of our second-generation ASIC, which has been reengineered to meet the advanced requirements of our Gen-II devices.



We have been working diligently with the ASX to facilitate the lifting of our trading suspension, ensuring full compliance by addressing all inquiries and regulatory requirements. We continue to work closely with the ASX to ensure compliance is met, and we anticipate will lead to the resumption of trading in due course.

With that, I will now proceed to the formal items of business as outlined in the Notice of Meeting.